

TechConnect Ventures
Sprint Challenge Brief:
Innovations in sustainable multilayer packaging technologies

BACKGROUND

On behalf of multiple international corporations, TechConnect Ventures is seeking responses from innovators around the world describing innovations in multilayer packaging. Multilayer packaging is widely used due to its ability to provide performance that cannot be replicated with a single polymer layer. These ultrathin laminate materials integrate multiple functionalities that combine strength, sealability, moisture and gas barrier properties, machinability, and more, while ultimately maximizing the shelf-life and quality of the products they contain. However most multilayer packages contain anywhere between 3-12 layers which are extremely difficult to separate, limiting their overall recyclability and resulting in "spent" packages being incinerated or landfilled.

AREAS OF INTEREST

TechConnect Ventures' clients have a critical need to identify any solutions that can bring multilayer packaging materials in line with a more sustainable future supply chain. Relevant areas of interest include, but are not limited to, materials, designs or alternative approaches for:

- Chemical recycling
- Biodegradable/compostable materials for layers and adhesives
- Maintaining functionality with reduced number of layers
- Improved methods of delamination
- Blending methods for recycling

BUSINESS OPPORTUNITY FOR SOLVERS

All complete and eligible Entries will be included in our exclusive Innovation Opportunity Report that will be presented to the innovation-seeking clients and partners. Solvers with well-matched capabilities may be contacted directly by consortium members to discuss potential partnership opportunities. Top-rated Entries may also be invited to register or participate in an upcoming TechConnect Ventures event or pitch program.

PARTICIPATION RULES & GUIDELINES

1. You must complete the provided Submission webform on the Sprint Submission page.
2. You are encouraged to submit a short presentation or pitch deck. A template is available on the Submission page.
3. **DO NOT INCLUDE ANY INFORMATION MARKED CONFIDENTIAL, PROPRIETARY, SENSITIVE OR CLASSIFIED. SUBMISSIONS MARKED AS SUCH WILL NOT BE SHARED WITH CLIENTS.**

Solvers should review the [Rules](#) and [Guidelines](#) provided on the Sprint page for full details about participation, including submission criteria, eligibility information, and more.

QUESTIONS? Contact Executive Director, Nick Kacsandi at info@techconnectventures.com